



# EcoSIM

## First generation of optimized SIM cards

Designed for high-end SIM cards, the optimized plating of Linxens EcoSIM ensures high level of reliability and product performance. This solution offers an ideal compromise between performance, aesthetics and product optimization.

### Key Features

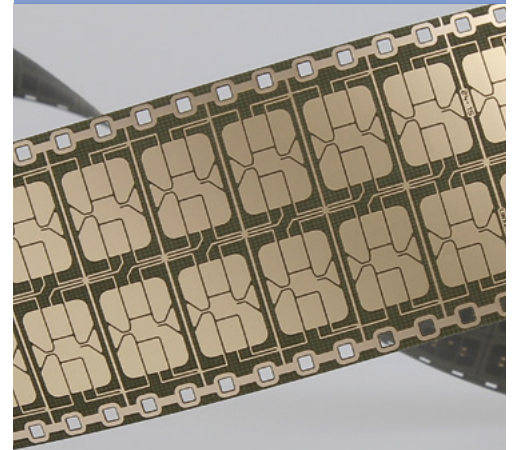
- Optimized Gold configuration on contact surface
- Homogeneous yellowish color
- Standard corrosion resistance

### Typical Product Designs

Form Factor	Part Number	Modules	Chip Dimension	Cavity
2FF / 3FF	9X12415	6	3.2 x 3 mm	No
2FF / 3FF	9X12416	6	1.8 x 1.8 mm	✓
2FF / 3FF	9X12501	6	2.6 x 2.6 mm	No
2FF / 3FF	9X13901	6	1.8 x 1.8 mm	✓
2FF / 3FF	9X13902	6	3.2 x 3 mm	No
2FF / 3FF	9X13704	6	1.8 x 1.8 mm	✓
2FF / 3FF	9X13705	6	3 x 3 mm	No
2FF / 3FF	9X21002	6	3.9 x 4.9 mm	✓
2FF / 3FF	9X21003	6	4.1 x ≤ 6 mm	No
4FF	9X13101	6	2.5 x 2.5 mm	✓
4FF	9X12420	6	1.8 x 1.8 mm	✓
4FF	9X21005	6	3.9 x 4.9 mm	✓
4FF	9X25301	6	3.1 x 3.6 mm	✓



MICROCONNECTORS



### Overview

#### Material

- Film base: Standard epoxy glass
- Copper: ED29 $\mu$
- Adhesive: High temperature modified epoxy MCHT

#### Thickness

- Total: 159  $\pm$  20  $\mu$ m
- Plating Thickness
  - Contact side
    - Ni: 1.6 (-0.6 +1.0)  $\mu$ m
    - Au: > 0.015  $\mu$ m
  - Back side:
    - Ni: 5 (-3 +3)  $\mu$ m
    - Au: 0.25 (-0.10 +0.20)  $\mu$ m

#### Plating Performance

Standard corrosion resistance

#### Compliance Labels

- ISO 10373
- ISO 7810

#### Application Area

- Telecom

#### Options

- Micro-etched / Fully-etched
- Colored tape: Red, blue, orange
- 2FF / 3FF / 4FF